

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00898	0.66	0.09702
	Doped silicon	Silicon (Si)	7440-21-3	1.35223	99.34	14.60298
		Subtotal		1.36121	100	14.7
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00648	2.0	0.07
	Lead alloy	Silver (Ag)	7440-22-4	0.0081	2.5	0.0875
	Lead alloy	Lead (Pb)	7439-92-1	0.30951	95.5	3.3425
		Subtotal		0.32409	100	3.5
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.25159	100.0	2.71699
		Subtotal		0.25159	100	2.71699
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03713	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01114	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03713	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.04708	99.77	400.0777
		Subtotal		37.13248	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.81355	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.86156	10.0	63.3
	Filler	Silica fused	60676-86-0	49.82327	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11723	0.2	1.266
		Subtotal		58.61561	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.31499	100.0	25
		Subtotal		2.31499	100	25
		Total		99.99997	100	1079.91699

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